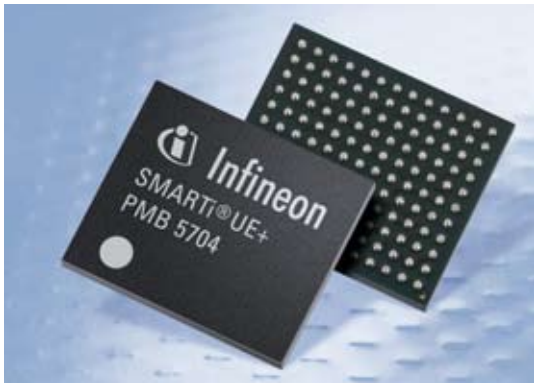
SMARTi UE+ PMB5704

First Single-Chip Diversity HSxPA/ EDGE Transceiver IC with pure digital DigRF V3.09 Interface and integrated front-end control



SMARTi UE+ is the world´s first single-chip diversity HSxPA/EDGE RF transceiver IC with a pure DigRF V3.09 interface for maximum HSDPA (14.4Mbps) and HSUPA (5,76Mbps) performance.

With a second receive path Rx diversity in SMARTi UE+ significantly increases the effective data throughput and the coverage area of mobile devices and PC cards and provides more capacity to the networks.

SMARTi UE+ has a single DigRF V3.09 interface to the digital baseband with a use case oriented programming for an easy system integration. It includes the control of RF front-end components eliminating the need for analog and digital control lines from the baseband.

Features

- Two receive paths for UMTS, EDGE, GPRS and GSM data conversion from RF into digital domain
- UMTS, EDGE, GPRS and GSM Tx paths for data conversion from digital into RF domain
- Pure digital 3G DigRF V3.09 interface
- HSDPA cat. 10 (14.4Mbps)
- HSUPA cat. 6 (5.76Mbps)
- TRP / TIS support
- Integrated analog and digital control of front-end components
- Simplified programming and calibration with on chip optimized autonomous sequence control system
- Low-power/smallest-size

Technology

- Based on Infineon's C11 130nm RF-CMOS Technology
- PG-WF2SGA-143 package
- 6.0 x 7.0 x 0.8mm
- Green product (lead (Pb) and halogen free)

Applications

- Worldwide 3GPP UMTS/EDGE, W-EDGE, H-EDGE, HSPA and HSUPA mobile data devices and mobile phones
- High Speed cellular data modems and PC Cards
- Multi-Band UMTS
- Quad-Band EDGE

RF Engine

Never stop thinking

How to reach us:
http://www.infineon.com

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Information

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Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

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